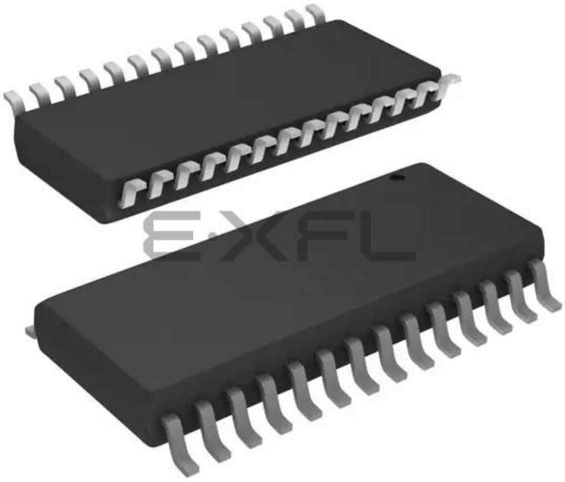
Microchip Technology - PIC18LC242T-I/SO Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	22
Program Memory Size	16KB (8K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 5x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lc242t-i-so

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TABLE 1-3: PIC18C4X2 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	DIP	PLCC	TQFP			
						PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-ups on all inputs.
RB0/INT0	33	36	8			
RB0				I/O	TTL	Digital I/O.
INT0				I	ST	External Interrupt 0.
RB1/INT1	34	37	9			
RB1				I/O	TTL	
INT1				I	ST	External Interrupt 1.
RB2/INT2	35	38	10			
RB2				I/O	TTL	Digital I/O.
INT2				I	ST	External Interrupt 2.
RB3/CCP2	36	39	11			
RB3				I/O	TTL	Digital I/O.
CCP2				I/O	ST	Capture2 input, Compare2 output, PWM2 output.
RB4	37	41	14	I/O	TTL	Digital I/O. Interrupt-on-change pin.
RB5	38	42	15	I/O	TTL	Digital I/O. Interrupt-on-change pin.
RB6	39	43	16	I/O I	TTL ST	Digital I/O. Interrupt-on-change pin. ICSP programming clock.
RB7	40	44	17	I/O I/O	TTL ST	Digital I/O. Interrupt-on-change pin. ICSP programming data.

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels I = Input
O = Output P = Power
OD = Open Drain (no P diode to V_{DD})

2.0 OSCILLATOR CONFIGURATIONS

2.1 Oscillator Types

The PIC18CXX2 can be operated in eight different oscillator modes. The user can program three configuration bits (FOSC2, FOSC1, and FOSC0) to select one of these eight modes:

1. LP Low Power Crystal
2. XT Crystal/Resonator
3. HS High Speed Crystal/Resonator
4. HS + PLL High Speed Crystal/Resonator with x 4 PLL enabled
5. RC External Resistor/Capacitor
6. RCIO External Resistor/Capacitor with RA6 I/O pin enabled
7. EC External Clock
8. ECIO External Clock with RA6 I/O pin enabled

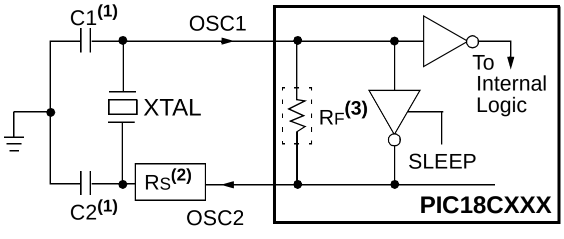
2.2 Crystal Oscillator/Ceramic Resonators

In XT, LP, HS or HS-PLL oscillator modes, a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation. Figure 2-1 shows the pin connections.

The PIC18CXX2 oscillator design requires the use of a parallel cut crystal.

Note: Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications.

FIGURE 2-1: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)



Note 1: See Table 2-1 and Table 2-2 for recommended values of C1 and C2.

2: A series resistor (RS) may be required for AT strip cut crystals.

3: RF varies with the osc mode chosen.

TABLE 2-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Ranges Tested:			
Mode	**Freq**	**C1**	**C2**
XT	455 kHz	68 - 100 pF	68 - 100 pF
	2.0 MHz	15 - 68 pF	15 - 68 pF
	4.0 MHz	15 - 68 pF	15 - 68 pF
HS	8.0 MHz	10 - 68 pF	10 - 68 pF
	16.0 MHz	10 - 22 pF	10 - 22 pF
These values are for design guidance only. See notes following this table.			
Resonators Used:			
455 kHz	Panasonic EFO-A455K04B		± 0.3%
2.0 MHz	Murata Erie CSA2.00MG		± 0.5%
4.0 MHz	Murata Erie CSA4.00MG		± 0.5%
8.0 MHz	Murata Erie CSA8.00MT		± 0.5%
16.0 MHz	Murata Erie CSA16.00MX		± 0.5%
All resonators used did not have built-in capacitors.			

Note 1: Higher capacitance increases the stability of the oscillator, but also increases the start-up time.

2: When operating below 3V VDD, it may be necessary to use high gain HS mode on lower frequency ceramic resonators.

3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components or verify oscillator performance.

TABLE 2-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATORS

Ranges Tested:			
Mode	**Freq**	**C1**	**C2**
LP	32.0 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1.0 MHz	15 pF	15 pF
	4.0 MHz	15 pF	15 pF
HS	4.0 MHz	15 pF	15 pF
	8.0 MHz	15-33 pF	15-33 pF
	20.0 MHz	15-33 pF	15-33 pF
	25.0 MHz	15-33 pF	15-33 pF
These values are for design guidance only. See notes following this table.			
Crystals Used			
32.0 kHz	Epson C-001R32.768K-A	± 20 PPM	
200 kHz	STD XTL 200.000kHz	± 20 PPM	
1.0 MHz	ECS ECS-10-13-1	± 50 PPM	
4.0 MHz	ECS ECS-40-20-1	± 50 PPM	
8.0 MHz	Epson CA-301 8.000M-C	± 30 PPM	
20.0 MHz	Epson CA-301 20.000M-C	± 30 PPM	

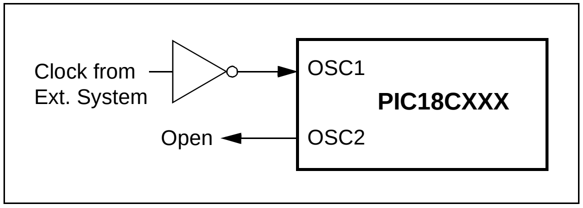
Note 1: Higher capacitance increases the stability of the oscillator, but also increases the start-up time.

2: Rs may be required in HS mode, as well as XT mode, to avoid overdriving crystals with low drive level specification.

3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components or verify oscillator performance.

An external clock source may also be connected to the OSC1 pin in these modes, as shown in Figure 2-2.

FIGURE 2-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP CONFIGURATION)

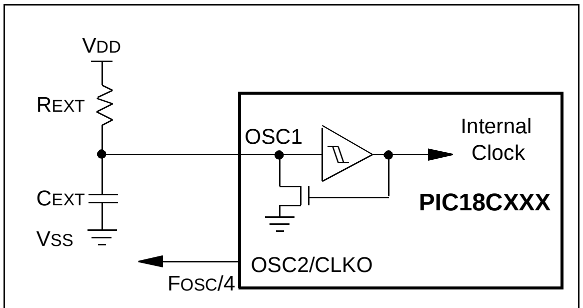


2.3 RC Oscillator

For timing insensitive applications, the “RC” and "RCIO" device options offer additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (REXT) and capacitor (CEXT) values and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low CEXT values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 2-3 shows how the R/C combination is connected.

In the RC oscillator mode, the oscillator frequency divided by 4 is available on the OSC2 pin. This signal may be used for test purposes or to synchronize other logic.

FIGURE 2-3: RC OSCILLATOR MODE



Recommended values: 3 kΩ ≤ REXT ≤ 100 kΩ
CEXT > 20pF

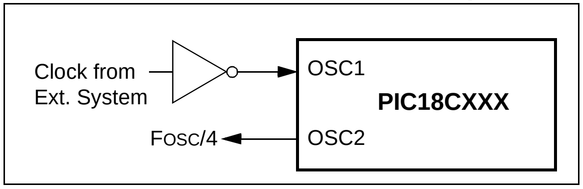
The RCIO oscillator mode functions like the RC mode, except that the OSC2 pin becomes an additional general purpose I/O pin. The I/O pin becomes bit 6 of PORTA (RA6).

2.4 External Clock Input

The EC and ECIO oscillator modes require an external clock source to be connected to the OSC1 pin. The feedback device between OSC1 and OSC2 is turned off in these modes to save current. There is no oscillator start-up time required after a Power-on Reset or after a recovery from SLEEP mode.

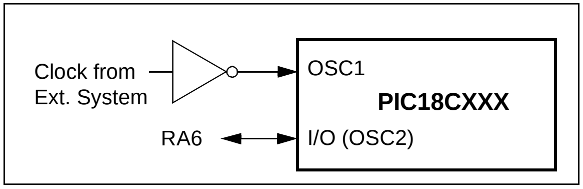
In the EC oscillator mode, the oscillator frequency divided by 4 is available on the OSC2 pin. This signal may be used for test purposes or to synchronize other logic. Figure 2-4 shows the pin connections for the EC oscillator mode.

FIGURE 2-4: EXTERNAL CLOCK INPUT OPERATION (EC OSC CONFIGURATION)



The ECIO oscillator mode functions like the EC mode, except that the OSC2 pin becomes an additional general purpose I/O pin. The I/O pin becomes bit 6 of PORTA (RA6). Figure 2-5 shows the pin connections for the ECIO oscillator mode.

FIGURE 2-5: EXTERNAL CLOCK INPUT OPERATION (ECIO CONFIGURATION)



2.5 HS/PLL

A Phase Locked Loop circuit is provided as a programmable option for users that want to multiply the frequency of the incoming crystal oscillator signal by 4. For an input clock frequency of 10 MHz, the internal clock frequency will be multiplied to 40 MHz. This is useful for customers who are concerned with EMI due to high frequency crystals.

The PLL can only be enabled when the oscillator configuration bits are programmed for HS mode. If they are programmed for any other mode, the PLL is not enabled and the system clock will come directly from OSC1.

The PLL is one of the modes of the FOSC<2:0> configuration bits. The oscillator mode is specified during device programming.

A PLL lock timer is used to ensure that the PLL has locked before device execution starts. The PLL lock timer has a time-out that is called TPLL.

FIGURE 2-6: PLL BLOCK DIAGRAM

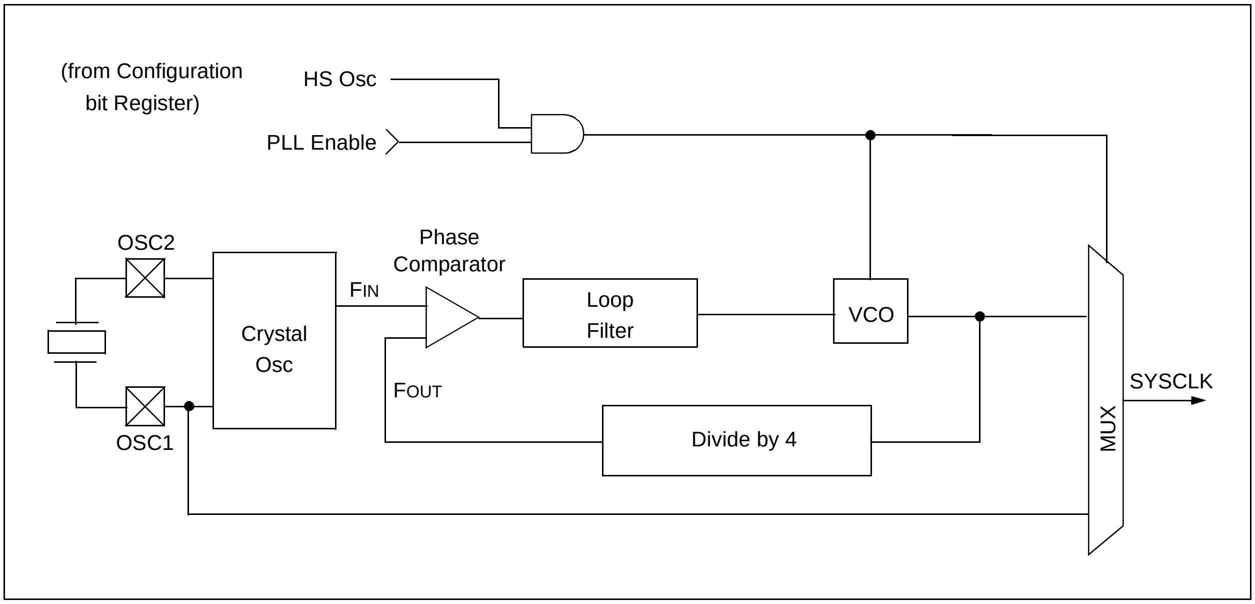


FIGURE 4-1: PROGRAM MEMORY MAP AND STACK FOR PIC18C442/242

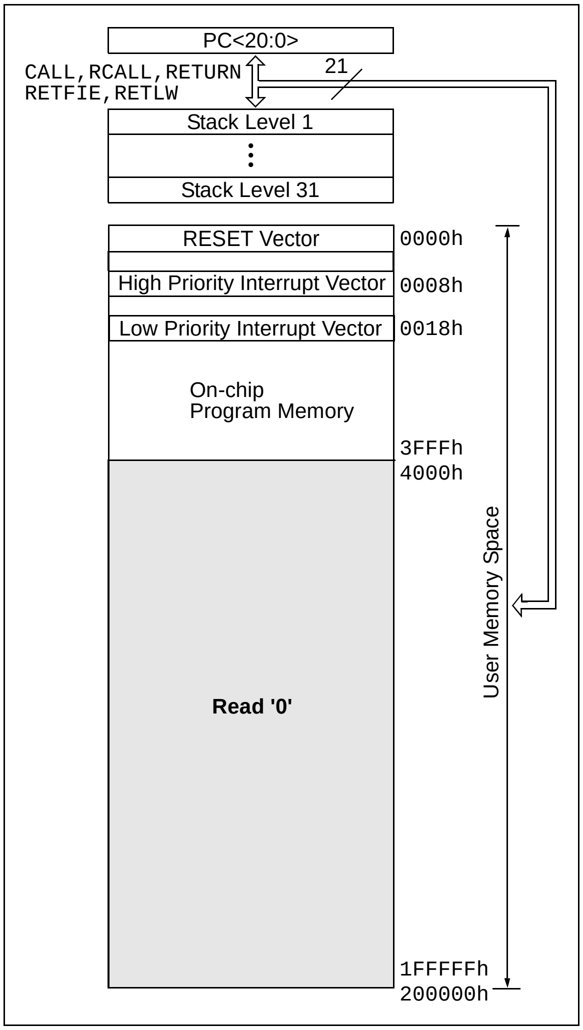
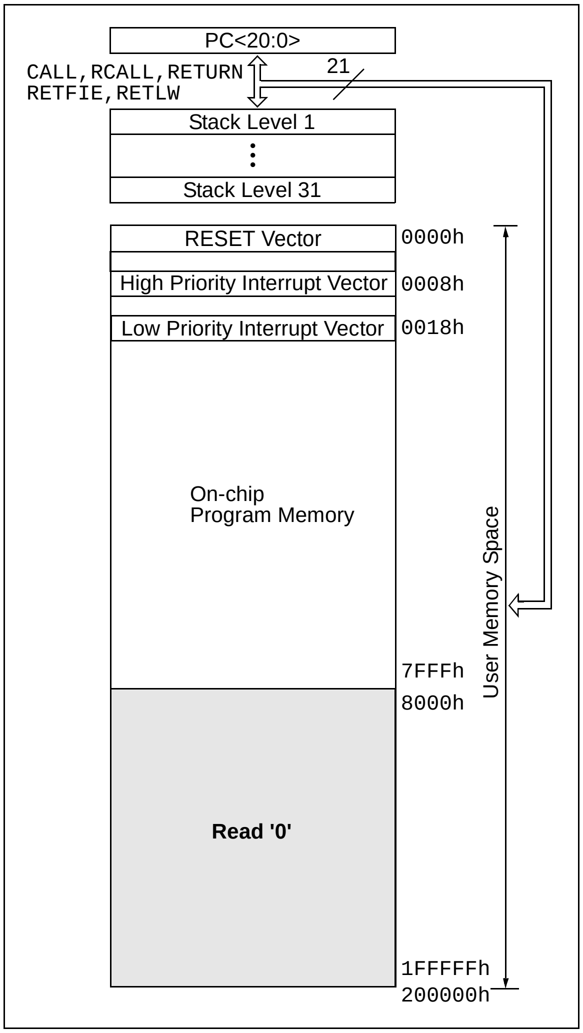


FIGURE 4-2: PROGRAM MEMORY MAP AND STACK FOR PIC18C452/252



4.13 STATUS Register

The STATUS register, shown in Register 4-2, contains the arithmetic status of the ALU. The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC, C, OV or N bits, then the write to these five bits is disabled. These bits are set or cleared according to the device logic. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper three bits and set the Z bit. This leaves the STATUS register as `000u u1uu` (where `u` = unchanged).

It is recommended, therefore, that only `BCF`, `BSF`, `SWAPF`, `MOVFF` and `MOVWF` instructions are used to alter the STATUS register, because these instructions do not affect the Z, C, DC, OV or N bits from the STATUS register. For other instructions not affecting any status bits, see Table 19-2.

Note:	The C and DC bits operate as a $\overline{\text{borrow}}$ and digit borrow bit respectively, in subtraction.

REGISTER 4-2: STATUS REGISTER

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	N	OV	Z	DC	C
bit 7							bit 0

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **N:** Negative bit
This bit is used for signed arithmetic (2's complement). It indicates whether the result was negative, (ALU MSB = 1).
`1` = Result was negative
`0` = Result was positive

bit 3 **OV:** Overflow bit
This bit is used for signed arithmetic (2's complement). It indicates an overflow of the 7-bit magnitude, which causes the sign bit (bit7) to change state.
`1` = Overflow occurred for signed arithmetic (in this arithmetic operation)
`0` = No overflow occurred

bit 2 **Z:** Zero bit
`1` = The result of an arithmetic or logic operation is zero
`0` = The result of an arithmetic or logic operation is not zero

bit 1 **DC:** Digit carry/$\overline{\text{borrow}}$ bit
For `ADDWF`, `ADDLW`, `SUBLW`, and `SUBWF` instructions
`1` = A carry-out from the 4th low order bit of the result occurred
`0` = No carry-out from the 4th low order bit of the result

Note: For $\overline{\text{borrow}}$, the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the bit 4 or bit 3 of the source register.

bit 0 **C:** Carry/$\overline{\text{borrow}}$ bit
For `ADDWF`, `ADDLW`, `SUBLW`, and `SUBWF` instructions
`1` = A carry-out from the Most Significant bit of the result occurred
`0` = No carry-out from the Most Significant bit of the result occurred

Note: For $\overline{\text{borrow}}$, the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high or low order bit of the source register.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

7.1 INTCON Registers

The INTCON Registers are readable and writable registers, which contains various enable, priority, and flag bits.

REGISTER 7-1: INTCON REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF
bit 7							bit 0

bit 7 **GIE/GIEH:** Global Interrupt Enable bit
When IPEN = 0:
1 = Enables all unmasked interrupts
0 = Disables all interrupts
When IPEN = 1:
1 = Enables all high priority interrupts
0 = Disables all high priority interrupts

bit 6 **PEIE/GIEL:** Peripheral Interrupt Enable bit
When IPEN = 0:
1 = Enables all unmasked peripheral interrupts
0 = Disables all peripheral interrupts
When IPEN = 1:
1 = Enables all low priority peripheral interrupts
0 = Disables all low priority peripheral interrupts

bit 5 **TMR0IE:** TMR0 Overflow Interrupt Enable bit
1 = Enables the TMR0 overflow interrupt
0 = Disables the TMR0 overflow interrupt

bit 4 **INT0IE:** INT0 External Interrupt Enable bit
1 = Enables the INT0 external interrupt
0 = Disables the INT0 external interrupt

bit 3 **RBIE:** RB Port Change Interrupt Enable bit
1 = Enables the RB port change interrupt
0 = Disables the RB port change interrupt

bit 2 **TMR0IF:** TMR0 Overflow Interrupt Flag bit
1 = TMR0 register has overflowed (must be cleared in software)
0 = TMR0 register did not overflow

bit 1 **INT0IF:** INT0 External Interrupt Flag bit
1 = The INT0 external interrupt occurred (must be cleared in software)
0 = The INT0 external interrupt did not occur

bit 0 **RBIF:** RB Port Change Interrupt Flag bit
1 = At least one of the RB7:RB4 pins changed state (must be cleared in software)
0 = None of the RB7:RB4 pins have changed state

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR reset	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit, or the global enable bit. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt. This feature allows for software polling.

13.3 Capture Mode

In Capture mode, CCPR1H:CCPR1L captures the 16-bit value of the TMR1 or TMR3 registers when an event occurs on pin RC2/CCP1. An event is defined as:

- every falling edge
- every rising edge
- every 4th rising edge
- every 16th rising edge

An event is selected by control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). When a capture is made, the interrupt request flag bit CCP1IF (PIR1<2>) is set. It must be cleared in software. If another capture occurs before the value in register CCPR1 is read, the old captured value will be lost.

13.3.1 CCP PIN CONFIGURATION

In Capture mode, the RC2/CCP1 pin should be configured as an input by setting the TRISC<2> bit.

Note:	If the RC2/CCP1 is configured as an output, a write to the port can cause a capture condition.

13.3.2 TIMER1/TIMER3 MODE SELECTION

The timers that are to be used with the capture feature (either Timer1 and/or Timer3) must be running in Timer mode or Synchronized Counter mode. In Asynchronous Counter mode, the capture operation may not work. The timer to be used with each CCP module is selected in the T3CON register.

13.3.3 SOFTWARE INTERRUPT

When the Capture mode is changed, a false capture interrupt may be generated. The user should keep bit CCP1IE (PIE1<2>) clear to avoid false interrupts and should clear the flag bit, CCP1IF, following any such change in operating mode.

13.3.4 CCP PRESCALER

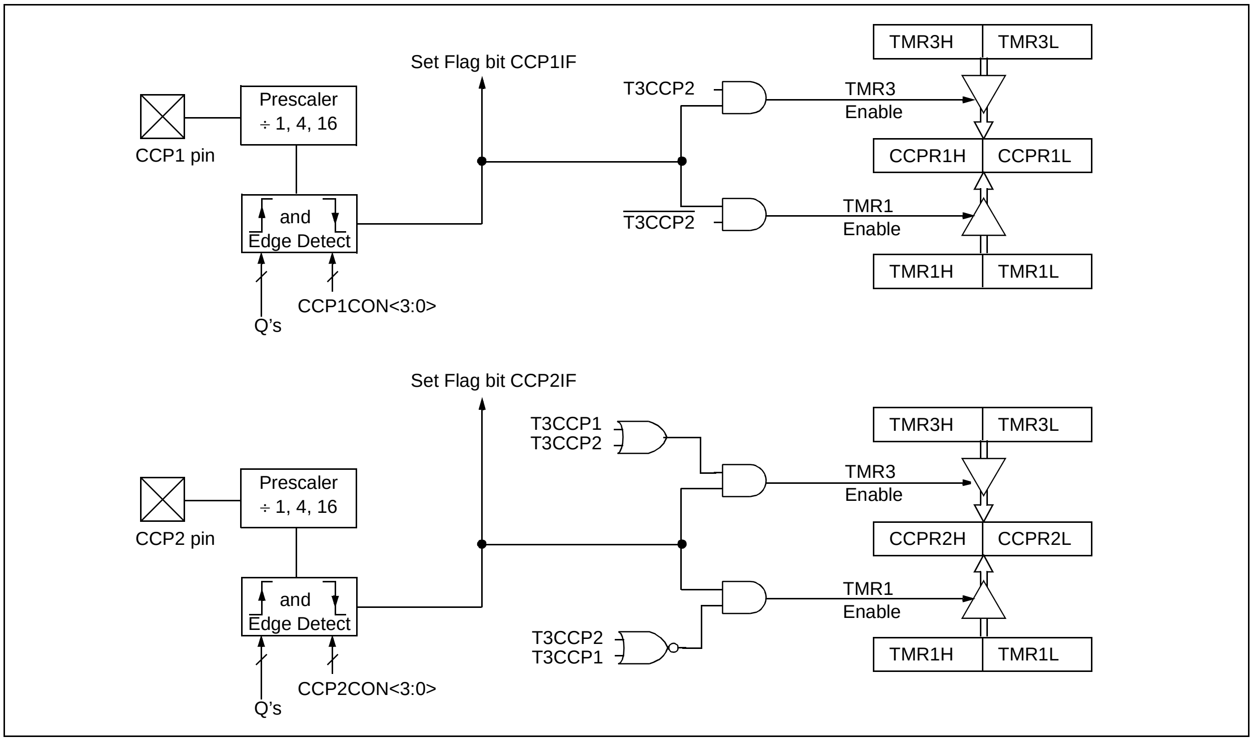
There are four prescaler settings, specified by bits CCP1M3:CCP1M0. Whenever the CCP module is turned off, or the CCP module is not in Capture mode, the prescaler counter is cleared. This means that any RESET will clear the prescaler counter.

Switching from one capture prescaler to another may generate an interrupt. Also, the prescaler counter will not be cleared, therefore, the first capture may be from a non-zero prescaler. Example 13-1 shows the recommended method for switching between capture prescalers. This example also clears the prescaler counter and will not generate the “false” interrupt.

EXAMPLE 13-1: CHANGING BETWEEN CAPTURE PRESCALERS

```
CLRF    CCP1CON, F  ; Turn CCP module off
MOVLW  NEW_CAPT_PS  ; Load WREG with the
                    ; new prescaler mode
                    ; value and CCP ON
MOVWF  CCP1CON      ; Load CCP1CON with
                    ; this value
```

FIGURE 13-1: CAPTURE MODE OPERATION BLOCK DIAGRAM



14.3 SPI Mode

The SPI mode allows 8-bits of data to be synchronously transmitted and received simultaneously. All four modes of SPI are supported. To accomplish communication, typically three pins are used:

- Serial Data Out (SDO) - RC5/SDO
- Serial Data In (SDI) - RC4/SDI/SDA
- Serial Clock (SCK) - RC3/SCK/SCL/LVOIN

Additionally, a fourth pin may be used when in a Slave mode of operation:

- Slave Select ($\overline{SS}$) - RA5/$\overline{SS}$/AN4

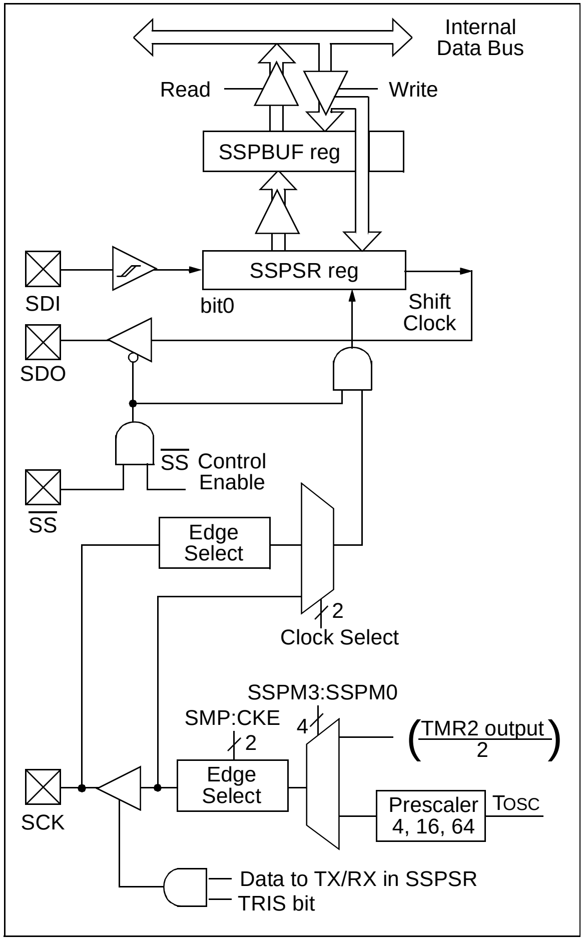
14.3.1 OPERATION

When initializing the SPI, several options need to be specified. This is done by programming the appropriate control bits (SSPCON1<5:0>) and SSPSTAT<7:6>. These control bits allow the following to be specified:

- Master mode (SCK is the clock output)
- Slave mode (SCK is the clock input)
- Clock Polarity (Idle state of SCK)
- Data input sample phase (middle or end of data output time)
- Clock edge (output data on rising/falling edge of SCK)
- Clock Rate (Master mode only)
- Slave Select mode (Slave mode only)

Figure 14-1 shows the block diagram of the MSSP module, when in SPI mode.

FIGURE 14-1: MSSP BLOCK DIAGRAM (SPI MODE)



The MSSP consists of a transmit/receive shift register (SSPSR) and a buffer register (SSPBUF). The SSPSR shifts the data in and out of the device, MSb first. The SSPBUF holds the data that was written to the SSPSR, until the received data is ready. Once the 8-bits of data have been received, that byte is moved to the SSPBUF register. Then the buffer full detect bit, BF (SSPSTAT<0>), and the interrupt flag bit, SSPIF, are set. This double buffering of the received data (SSPBUF) allows the next byte to start reception before reading the data that was just received. Any write to the SSPBUF register during transmission/reception of data will be ignored, and the write collision detect bit, WCOL (SSPCON1<7>), will be set. User software must clear the WCOL bit so that it can be determined if the following write(s) to the SSPBUF register completed successfully.

FIGURE 14-25: BUS COLLISION DURING START CONDITION (SCL = 0)

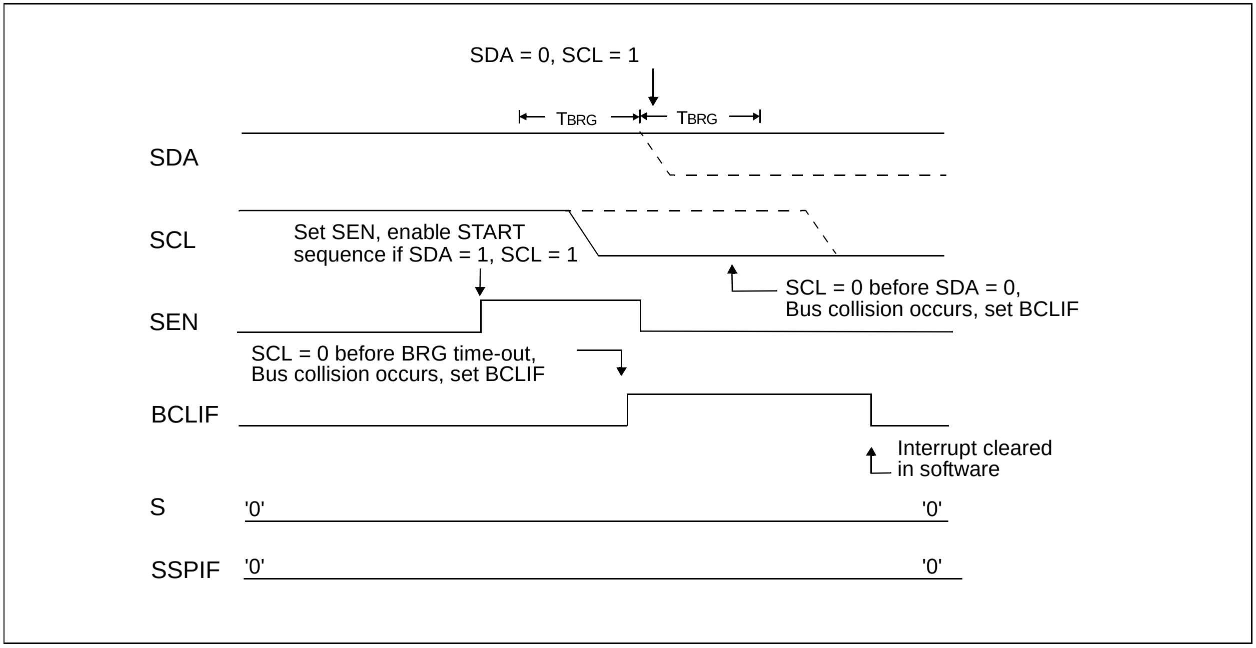

SDA = 0, SCL = 1
TBRG
TBRG
SDA
SCL
Set SEN, enable START sequence if SDA = 1, SCL = 1
SCL = 0 before SDA = 0, Bus collision occurs, set BCLIF
SEN
SCL = 0 before BRG time-out, Bus collision occurs, set BCLIF
BCLIF
Interrupt cleared in software
S
'0'
'0'
SSPIF
'0'
'0'

FIGURE 14-26: BRG RESET DUE TO SDA ARBITRATION DURING START CONDITION

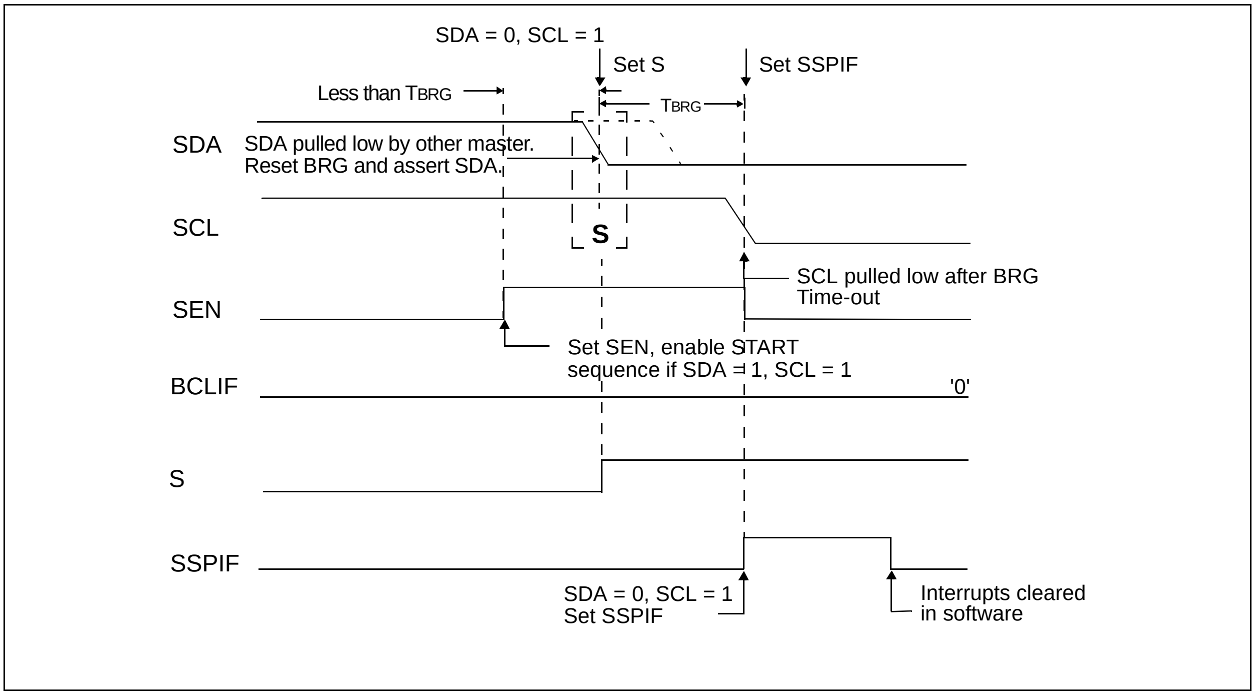
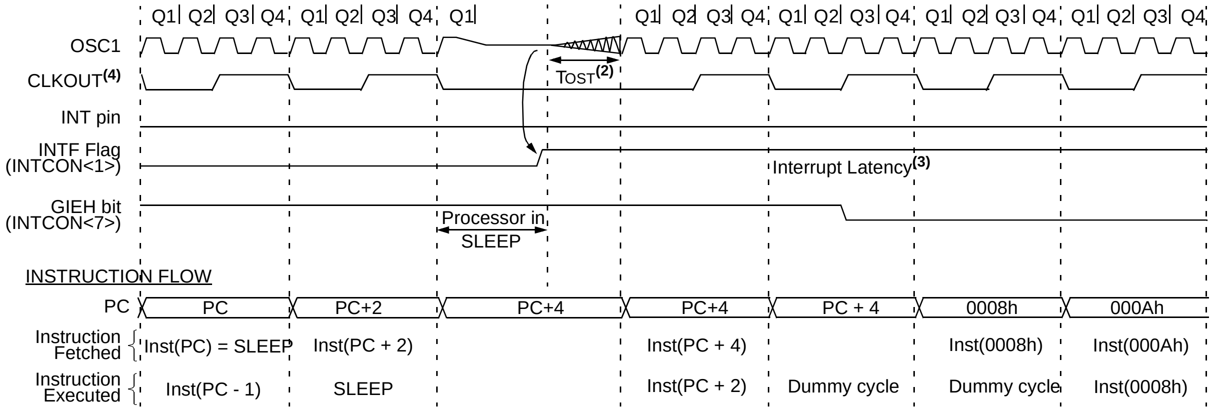

SDA = 0, SCL = 1
Set S
Set SSPIF
Less than TBRG
TBRG
SDA
SDA pulled low by other master. Reset BRG and assert SDA.
SCL
S
SCL pulled low after BRG Time-out
SEN
Set SEN, enable START sequence if SDA = 1, SCL = 1
BCLIF
'0'
S
SSPIF
SDA = 0, SCL = 1 Set SSPIF
Interrupts cleared in software

FIGURE 18-2: WAKE-UP FROM SLEEP THROUGH INTERRUPT[1,2]



Note 1: XT, HS or LP oscillator mode assumed.
2: GIE = '1' assumed. In this case, after wake- up, the processor jumps to the interrupt routine. If GIE = '0', execution will continue in-line.
3: TOST = 1024TOSC (drawing not to scale) This delay will not occur for RC and EC osc modes.
4: CLKOUT is not available in these osc modes, but shown here for timing reference.

18.4 Program Verification/Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

Note: Microchip Technology does not recommend code protecting windowed devices.

18.5 ID Locations

Five memory locations (200000h - 200004h) are designated as ID locations, where the user can store checksum or other code identification numbers. These locations are accessible during normal execution through the `TBLRD` instruction or during program/verify. The ID locations can be read when the device is code protected.

18.6 In-Circuit Serial Programming

PIC18CXXX microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

MULLW Multiply Literal with WREG

Syntax: [*label*] MULLW k

Operands: $0 \le k \le 255$

Operation: (WREG) x k → PRODH:PRODL

Status Affected: None

Encoding:

`0000`	`1101`	`kkkk`	`kkkk`

Description: An unsigned multiplication is carried out between the contents of WREG and the 8-bit literal 'k'. The 16-bit result is placed in PRODH:PRODL register pair. PRODH contains the high byte.
WREG is unchanged.
None of the status flags are affected.
Note that neither overflow, nor carry is possible in this operation. A zero result is possible but not detected.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write registers PRODH: PRODL

<u>Example</u>: `MULLW 0xC4`

Before Instruction

```
WREG    =  0xE2
PRODH   =  ?
PRODL   =  ?
```

After Instruction

```
WREG    =  0xE2
PRODH   =  0xAD
PRODL   =  0x08
```

MULWF Multiply WREG with f

Syntax: [*label*] MULWF f [,a]

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: (WREG) x (f) → PRODH:PRODL

Status Affected: None

Encoding:

`0000`	`001a`	`ffff`	`ffff`

Description: An unsigned multiplication is carried out between the contents of WREG and the register file location 'f'. The 16-bit result is stored in the PRODH:PRODL register pair. PRODH contains the high byte.
Both WREG and 'f' are unchanged.
None of the status flags are affected.
Note that neither overflow, nor carry is possible in this operation. A zero result is possible but not detected. If ‘a’ is 0, the Access Bank will be selected, overriding the BSR value. If ‘a’= 1, then the bank will be selected as per the BSR value (default).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write registers PRODH: PRODL

<u>Example</u>: `MULWF REG, 1`

Before Instruction

```
WREG    =  0xC4
REG     =  0xB5
PRODH   =  ?
PRODL   =  ?
```

After Instruction

```
WREG    =  0xC4
REG     =  0xB5
PRODH   =  0x8A
PRODL   =  0x94
```

RCALL Relative Call

Syntax:	[*label*] RCALL n
Operands:	-1024 ≤ n ≤ 1023
Operation:	(PC) + 2 → TOS, (PC) + 2 + 2n → PC
Status Affected:	None
Encoding:	`1101` `1nnn` `nnnn` `nnnn`
Description:	Subroutine call with a jump up to 1K from the current location. First, return address (PC+2) is pushed onto the stack. Then, add the 2’s complement number ’2n’ to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC+2+2n. This instruction is a two-cycle instruction.
Words:	1
Cycles:	2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'n' Push PC to stack	Process Data	Write to PC
No operation	No operation	No operation	No operation

Example: `HERE      RCALL` Jump

Before Instruction

```
PC  =   Address(HERE)
```

After Instruction

```
PC  =   Address(Jump)
TOS =   Address (HERE+2)
```

RESET Reset

Syntax:	[*label*] RESET
Operands:	None
Operation:	Reset all registers and flags that are affected by a $\overline{\text{MCLR}}$ reset.
Status Affected:	All
Encoding:	`0000` `0000` `1111` `1111`
Description:	This instruction provides a way to execute a $\overline{\text{MCLR}}$ Reset in software.
Words:	1
Cycles:	1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Start reset	No operation	No operation

Example: `RESET`

After Instruction

```
Registers   =   Reset Value
Flags*      =   Reset Value
```

RETURN Return from Subroutine

Syntax: [*label*] RETURN [s]

Operands: s ∈ [0,1]

Operation: (TOS) → PC,
if s = 1
(WS) → WREG,
(STATUSS) → STATUS,
(BSRS) → BSR,
PCLATU, PCLATH are unchanged

Status Affected: None

Encoding:

0000	0000	0001	001s

Description: Return from subroutine. The stack is popped and the top of the stack (TOS) is loaded into the program counter. If ‘s’= 1, the contents of the shadow registers WS, STATUSS and BSRS are loaded into their corresponding registers, WREG, STATUS and BSR. If ‘s’ = 0, no update of these registers occurs (default).

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	Process Data	pop PC from stack
No operation	No operation	No operation	No operation

Example: `RETURN`

After Interrupt

```
PC  = TOS
```

RLCF Rotate Left f through Carry

Syntax: [*label*] RLCF f [,d [,a]

Operands: 0 ≤ f ≤ 255
d ∈ [0,1]
a ∈ [0,1]

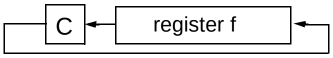
Operation: (f<n>) → dest<n+1>,
(f<7>) → C,
(C) → dest<0>

Status Affected: C,N,Z

Encoding:

0011	01da	ffff	ffff

Description: The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0, the result is placed in WREG. If 'd' is 1, the result is stored back in register 'f' (default). If ‘a’ is 0, the Access Bank will be selected, overriding the BSR value. If ’a’ = 1, then the bank will be selected as per the BSR value (default).



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: `RLCF REG, 0, 0`

Before Instruction

```
REG     =   1110 0110
C       =   0
```

After Instruction

```
REG     =   1110 0110
WREG    =   1100 1100
C       =   1
```

21.1 DC Characteristics

PIC18LCXX2 (Industrial)	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial
PIC18CXX2 (Industrial, Extended)	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended

Param No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
	VDD	**Supply Voltage**					
D001		PIC18LCXX2	2.5	—	5.5	V	HS, XT, RC and LP osc mode
D001		PIC18CXX2	4.2	—	5.5	V	
D002	VDR	**RAM Data Retention Voltage(1)**	1.5	—	—	V	
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	—	—	0.7	V	See section on Power-on Reset for details
D004	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	See section on Power-on Reset for details
	VBOR	**Brown-out Reset Voltage**					
D005		PIC18LCXX2					
		BORV1:BORV0 = 11	2.5	—	2.66	V	
		BORV1:BORV0 = 10	2.7	—	2.86	V	
		BORV1:BORV0 = 01	4.2	—	4.46	V	
		BORV1:BORV0 = 00	4.5	—	4.78	V	
D005		PIC18CXX2					
		BORV1:BORV0 = 1x	N.A.	—	N.A.	V	Not in operating voltage range of device
		BORV1:BORV0 = 01	4.2	—	4.46	V	
		BORV1:BORV0 = 00	4.5	—	4.78	V	

Legend: Shading of rows is to assist in readability of the table.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode, or during a device RESET, without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD
MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS, and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR,...).

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

FIGURE 22-5: TYPICAL IDD vs. FOSC OVER VDD (XT MODE)

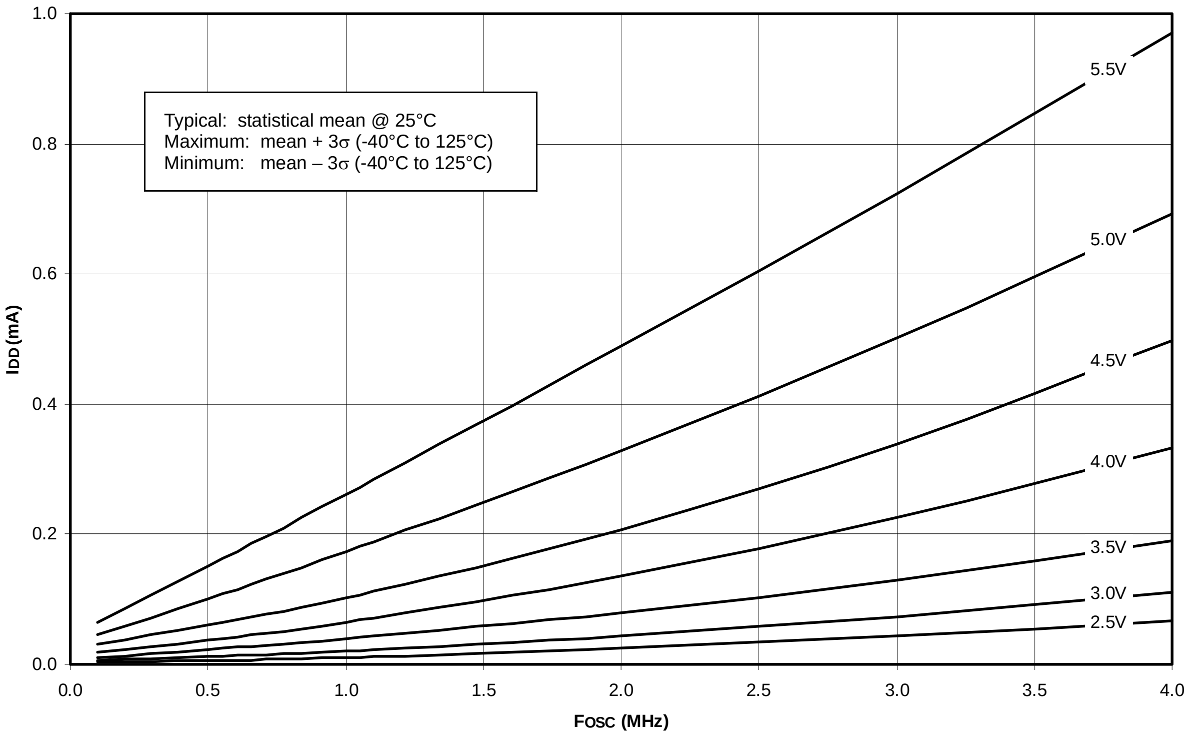
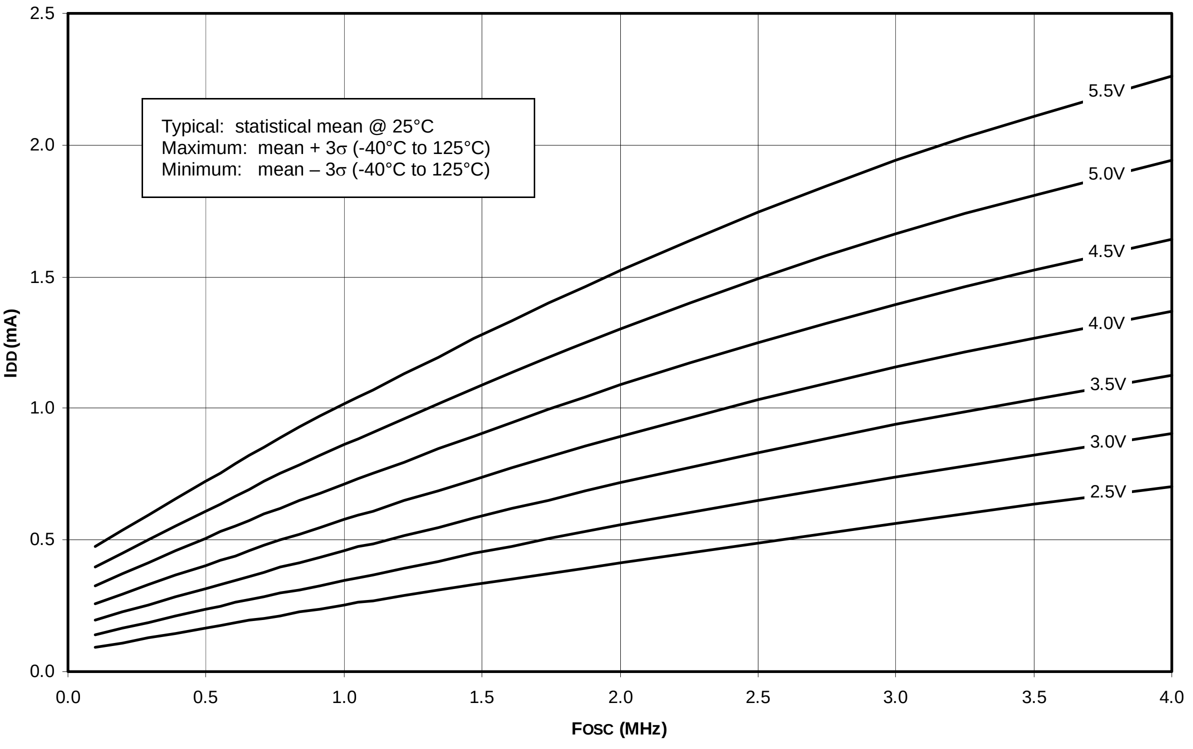


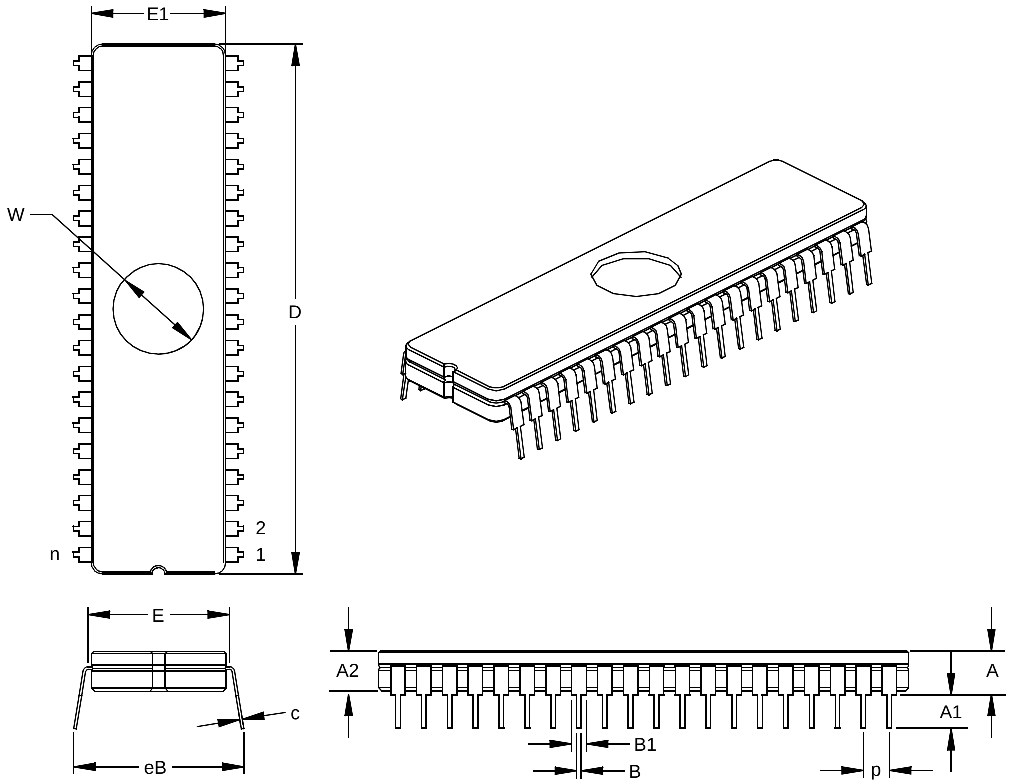
FIGURE 22-6: MAXIMUM IDD vs. FOSC OVER VDD (XT MODE)



NOTES:

40-Lead Ceramic Dual In-line with Window (JW) – 600 mil (CERDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		40			40	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.185	.205	.225	4.70	5.21	5.72
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.030	.045	.060	0.76	1.14	1.52
Shoulder to Shoulder Width	E	.595	.600	.625	15.11	15.24	15.88
Ceramic Pkg. Width	E1	.514	.520	.526	13.06	13.21	13.36
Overall Length	D	2.040	2.050	2.060	51.82	52.07	52.32
Tip to Seating Plane	L	.135	.140	.145	3.43	3.56	3.68
Lead Thickness	c	.008	.011	.014	0.20	0.28	0.36
Upper Lead Width	B1	.050	.053	.055	1.27	1.33	1.40
Lower Lead Width	B	.016	.020	.023	0.41	0.51	0.58
Overall Row Spacing §	eB	.610	.660	.710	15.49	16.76	18.03
Window Diameter	W	.340	.350	.360	8.64	8.89	9.14

* Controlling Parameter
§ Significant Characteristic
JEDEC Equivalent: MO-103
Drawing No. C04-014

APPENDIX C: CONVERSION CONSIDERATIONS

This appendix discusses the considerations for converting from previous versions of a device to the ones listed in this data sheet. Typically, these changes are due to the differences in the process technology used. An example of this type of conversion is from a PIC16C74A to a PIC16C74B.

Not Applicable

APPENDIX D: MIGRATION FROM BASELINE TO ENHANCED DEVICES

This section discusses how to migrate from a Baseline device (i.e., PIC16C5X) to an Enhanced MCU device (i.e., PIC18CXXX).

The following are the list of modifications over the PIC16C5X microcontroller family:

Not Currently Available